EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|--------|---|--|---------------------|---------|------------------|
| L2 | 1 | 10/695249 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 09:50 |
| L4 | 28 | ("20020175424" "20040157433" "602 2808" "6022808" "6100195" "6147408 " "6291082" "6291082" "6444567" "64 44567" "6479389" "6551872" "662407 5" "6696761" "6800554" "6924234"). PN. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:21 |
| L5 | 152 | ("20020175424" "20040157433" "602 2808" "6022808" "6100195" "6147408 " "6291082" "6291082" "6444567" "64 44567" "6479389" "6551872" "662407 5" "6696761" "6800554" "6924234") | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:19 |
| L6 | 12800 | 438/637-638,672-673,700,618-624, 687.ccls. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:22 |
| L8 | . 5858 | 6 and copper | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:23 |
| L9 | 4664 | 8 and oxide | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:23 |
| L10 | 4437 | 9 and etch\$3 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:24 |

EÁST Search History

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|-----|------|--|--|----|----|------------------|
| L11 | 1770 | 9 and (plating electroless) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:25 |
| L12 | 1233 | 10 and acid\$3 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:38 |
| L13 | 421 | 12 and (metal with diffus\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:41 |
| L16 | 421 | 13 and (metal with diffus\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:42 |
| L17 | 27 | 16 and (metal with noble) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:42 |
| L18 | 0 | (conductive near3 path with substrate and first adj material and second adj material and facilitating with diffusion and metal with copper and low adj solubility and oxide with etching with acidic and planarizing with comductive with path).clm. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/27 10:43 |